

STGF10NB60SD STGP10NB60SD

16 A, 600 V, low drop IGBT with soft and fast recovery diode

Features

- Low on-voltage drop (V_{CE(sat)})
- High current capability
- Very soft ultra fast recovery antiparallel diode

Applications

- Light dimmer
- Static relays
- Motor drive

Description

This IGBT utilizes the advanced Power MESH™ process featuring extremely low on-state voltage drop in low-frequency working conditions (up to 1 kHz).

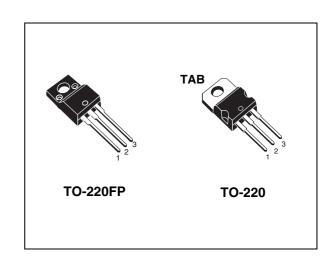


Figure 1. Internal schematic diagram

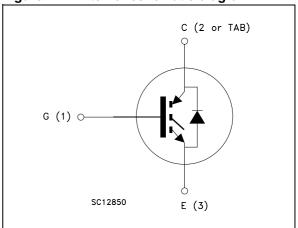


Table 1. Device summary

Order codes	Order codes Marking		Packaging
STGF10NB60SD	GF10NB60SD	TO-220FP	Tube
STGP10NB60SD	GP10NB60SD	TO-220	Tube

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1 Electrical ratings

Table 2. Absolute maximum ratings

Cymhol	Parameter	Va	lue	Umit	
Symbol	Parameter	STGF10NB60SD	STGP10NB60SD	Unit	
V _{CES}	Collector-emitter voltage (V _{GE} = 0)	6	00	V	
I _C ⁽¹⁾	Continuous collector current at $T_C = 25$ °C	23	29	Α	
I _C ⁽¹⁾	Continuous collector current at $T_C = 100 ^{\circ}\text{C}$		16	Α	
I _{CL} ⁽²⁾	I _{CL} (2) Turn-off latching current		20		
I _{CP} ⁽³⁾	Pulsed collector current	8	Α		
V_{GE}	Gate-emitter voltage	roltage ±20		٧	
I _F	Diode RMS forward current at $T_C = 25$ °C	orward current at T _C = 25 °C 20		Α	
I _{FSM}	Surge non repetitive forward current $t_p = 10$ ms sinusoidal	55		Α	
V _{ISO}	Isolation withstand voltage (RMS) from all three leads to external heatsink (t=1 s; $T_C = 25$ °C)	all 2500		V	
P _{TOT}	Total dissipation at T _C = 25 °C	5 °C 25 80		W	
T _j	Operating junction temperature	– 55 to 150		°C	

1. Calculated according to the iterative formula

$$I_{C}(T_{C}) = \frac{T_{j(max)} - T_{C}}{R_{thj-c} \times V_{CE(sat)(max)}(T_{j(max)}, I_{C}(T_{C}))}$$

- 2. Vclamp = 80% of V_{CES}, T_j =150 °C, R_G=1k Ω , V_{GE}=15 V
- 3. Pulse width limited by maximum junction temperature and turn-off within RBSOA

Table 3. Thermal data

Symbol Parameter		Val	Unit	
		STGF10NB60SD	STGP10NB60SD	
R _{thj-case}	Thermal resistance junction-case IGBT	5	1.56	°C/W
R _{thj-case}	Thermal resistance junction-case diode 5.6 2.2		°C/W	
R _{thj-amb}	Thermal resistance junction-ambient	62.5		°C/W

2 Electrical characteristics

 $(T_j = 25 \, ^{\circ}C \text{ unless otherwise specified})$

Table 4. Static

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)CES}	Collector-emitter breakdown voltage (V _{GE} = 0)	I _C = 250 μA	600			٧
V _{(BR)ECS}	Emitter-collector breakdown voltage (V _{GE} = 0)	I _C = 1 mA	20			٧
I _{GES}	Gate-emitter leakage current (V _{CE} = 0)	V _{GE} = ±20 V			±100	nA
I _{CES}	Collector cut-off current (V _{GE} = 0)	V _{CE} = 600 V V _{CE} = 600 V, T _j = 125 °C			10 100	μ Α μ Α
V _{GE(th)}	Gate threshold voltage	V _{CE} = V _{GE} , I _C = 250 μA	2.5		5	٧
V _{CE(sat)}	Collector-emitter saturation voltage	V_{GE} = 15 V, I_{C} = 5 A V_{GE} = 15 V, I_{C} = 10 A V_{GE} = 15 V, I_{C} = 10 A, T_{j} = 125 °C		1.15 1.35 1.25	1.75	V
9 _{fs} ⁽¹⁾	Forward transconductance	V _{CE} = 15 V _, I _C = 10 A	5			S

^{1.} Pulsed: Pulse duration = $300 \mu s$, duty cycle 1.5%

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C _{ies} C _{oes} C _{res}	Input capacitance Output capacitance Reverse transfer capacitance	V _{CE} = 25 V, f = 1 MHz, V _{GE} = 0	-	610 65 12	-	pF pF pF
Qg	Total gate charge	$V_{CE} = 400 \text{ V, } I_{C} = 10 \text{ A,}$ $V_{GE} = 15 \text{ V}$ (see Figure 19)		33		nC

Table 6. Switching on/off (inductive load)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)} t _r (di/dt) _{on}	Turn-on delay time Current rise time Turn-on current slope	V_{CC} = 480 V, I_{C} = 10 A R_{G} = 1 k Ω , V_{GE} = 15 V (see Figure 18)	-	0.7 0.46 8	-	μs μs Α/μs
$t_r(V_{off})$ $t_d(_{off})$ t_f	Off voltage rise time Turn-off delay time Current fall time	$V_{CC} = 480 \text{ V}, I_{C} = 10 \text{ A}$ $R_{G} = 1 \text{ k}\Omega, V_{GE} = 15 \text{ V}$ (see Figure 18)	-	2.2 1.2 1.2	-	μs
t _r (V _{off}) t _d (_{off}) t _f	Off voltage rise time Turn-off delay time Current fall time	$V_{CC} = 480 \text{ V}, I_{C} = 10 \text{ A}$ $R_{G} = 1 \text{ k}\Omega, V_{GE} = 15 \text{ V},$ $T_{j} = 125 \text{ °C}$ (see Figure 18)	-	3.8 1.2 1.9	-	μs

Table 7. Switching energy (inductive load)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
Eon ⁽¹⁾ E _{off} ⁽²⁾ E _{ts}	Turn-on switching losses Turn-off switching losses Total switching losses	V_{CC} = 480 V, I_{C} = 10 A R_{G} = 1 k Ω , V_{GE} = 15 V (see Figure 18)	-	0.6 5 5.6	-	mJ mJ mJ
E _{off} ⁽²⁾	Turn-off switching losses	$V_{CC} = 480 \text{ V, } I_{C} = 10 \text{ A}$ $R_{G} = 1 \text{ k}\Omega, V_{GE} = 15 \text{ V,}$ $T_{j} = 125 \text{ °C}$ (see Figure 18)	-	8		mJ

Eon is the turn-on losses when a typical diode is used in the test circuit. If the IGBT is offered in a package with a co-pack diode, the co-pack diode is used as external diode. IGBTs and diode are at the same temperature (25°C and 125°C)

Table 8. Collector-emitter diode

Symbol	Parameter	Test conditions	Min	Тур.	Max	Unit
V _F	Forward on-voltage	I _F = 10 A I _F = 10 A, T _C = 125 °C		1.4	2.2	V V
t _{rr} Q _{rr} I _{rrm}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_F = 7 \text{ A}, V_R = 40 \text{ V},$ di/dt = 100 A/ μ s (see Figure 21)		37 40 2.1		ns nC A
t _{rr} Q _{rr} I _{rrm}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_F = 7 \text{ A}, V_R = 40 \text{ V},$ $T_j = 125 \text{ °C},$ $di/dt = 100 \text{ A/}\mu\text{s}$ (see Figure 21)		61 98 3.2		ns nC A

^{2.} Turn-off losses include also the tail of the collector current.

2.1 Electrical characteristics (curves)

Figure 2. Output characteristics

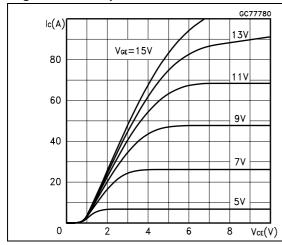


Figure 3. Transfer characteristics

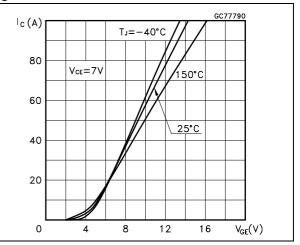
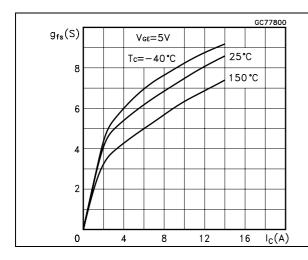


Figure 4. Transconductance

Figure 5. Collector-emitter on voltage vs. temperature



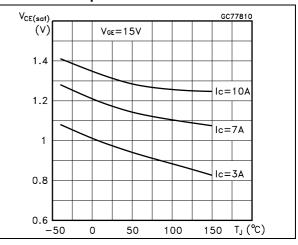
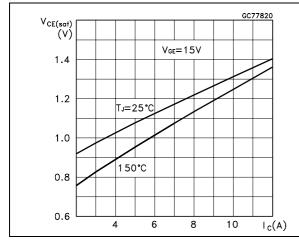
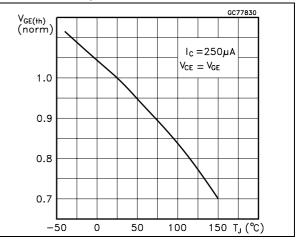


Figure 6. Collector-emitter on voltage vs. collector current

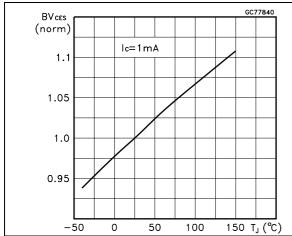
Figure 7. Normalized gate threshold vs. temperature





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Figure 8. Normalized breakdown voltage vs. Figure 9. Gate charge vs. gate-emitter temperature voltage



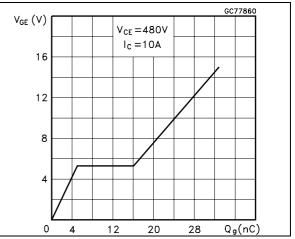


Figure 10. Capacitance variations

GC77850 C(pF) f=1MHz $V_{GE} = 0V$ 800 Cies 600 400 200 Coes Cres 0 5 10 15 20 $V_{CE}(V)$

Figure 11. Switching losses vs. temperature

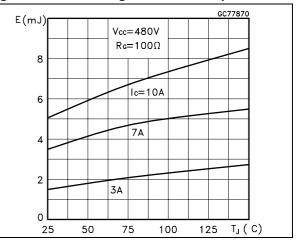
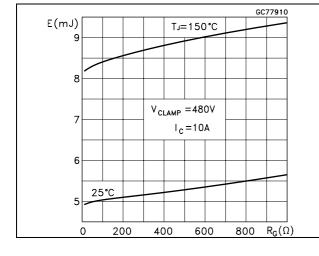


Figure 12. Switching losses vs. gate resistance

Figure 13. Switching losses vs. collector current



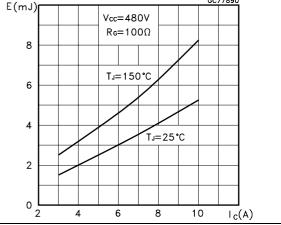


Figure 14. Thermal impedance for TO-220

Figure 15. Thermal impedance for TO-220FP

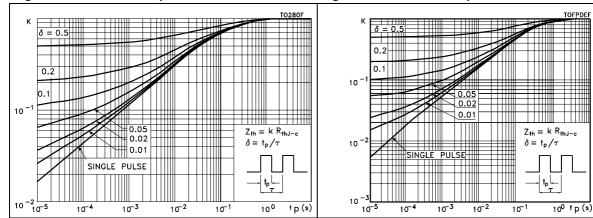
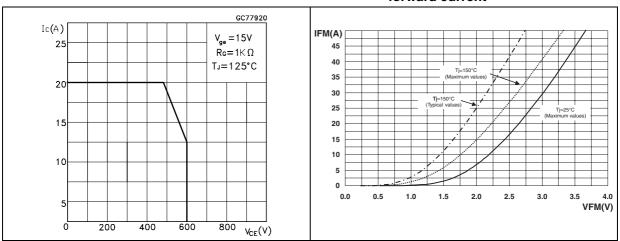


Figure 16. Turn-off SOA

Figure 17. Forward voltage drop versus forward current



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3 Test circuits

Figure 18. Test circuit for inductive load switching

Figure 19. Gate charge test circuit

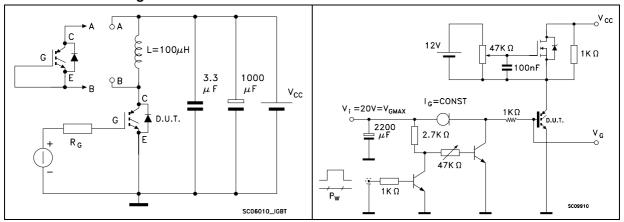
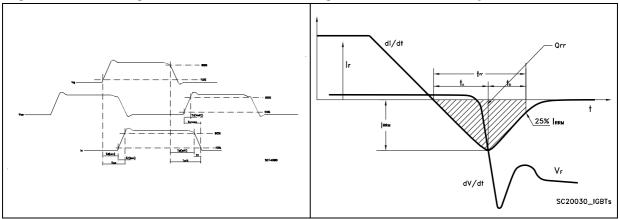


Figure 20. Switching waveforms

Figure 21. Diode recovery times waveform



4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

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Table 9. TO-220FP mechanical data

Dim.		mm.	
Dim.	Min.	Тур.	Max.
А	4.4		4.6
В	2.5		2.7
D	2.5		2.75
Е	0.45		0.7
F	0.75		1
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.2
G1	2.4		2.7
Н	10		10.4
L2		16	
L3	28.6		30.6
L4	9.8		10.6
L5	2.9		3.6
L6	15.9		16.4
L7	9		9.3
Dia	3		3.2

Figure 22. TO-220FP drawing

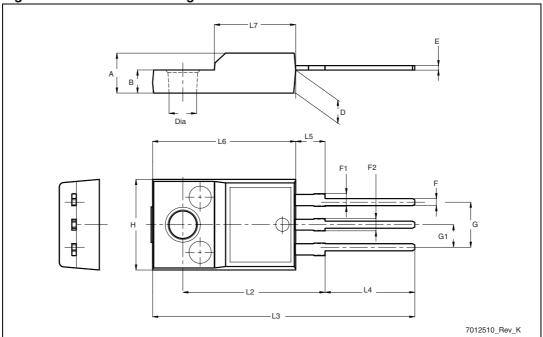


Table 10. TO-220 type A mechanical data

Dim		mm.	
Dim.	Min.	Тур.	Max.
А	4.40		4.60
b	0.61		0.88
b1	1.14		1.70
С	0.48		0.70
D	15.25		15.75
D1		1.27	
Е	10		10.40
е	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
ØP	3.75		3.85
Q	2.65		2.95

Figure 23. TO-220 type A drawing

5 Revision history

Table 11. Document revision history

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Date	Revision	Changes	
18-Nov-2005	1	New release.	
16-Dec-2010	2	Inserted device in TO-220FP. Updated <i>Table 2: Absolute maximum ratings</i> , <i>Table 8: Collectoremitter diode</i> and packages mechanical data <i>Section 4: Package mechanical data</i> .	
22-Sep-2011	3	Modified: unit value <i>Table 7 on page 5</i> , <i>Figure 2</i> and <i>Figure 3</i> on page 6.	

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